



Material Content Data Sheet



Sales Product Name	TLS820D0EL V50			Issued	25. January 2018			
MA#	MA001398412							
Package	PG-SSOP-14-5			Weight*	82.84 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.743	2.10	2.10	21042	21042
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		104	
	non noble metal	zinc	7440-66-6	0.034	0.04		416	
	non noble metal	iron	7439-89-6	0.689	0.83		8318	
wire	non noble metal	copper	7440-50-8	27.978	33.77	34.65	337744	346582
	non noble metal	copper	7440-50-8	0.070	0.08	0.08	841	841
	encapsulation	organic material	carbon black	1333-86-4	0.100	0.12		1207
plastics	plastics	epoxy resin	-	4.601	5.55		55538	
	inorganic material	silicondioxide	60676-86-0	45.306	54.71	60.38	546924	603669
leadfinish	non noble metal	tin	7440-31-5	0.976	1.18	1.18	11784	11784
plating	noble metal	silver	7440-22-4	0.768	0.93	0.93	9266	9266
glue	plastics	epoxy resin	-	0.141	0.17		1704	
	noble metal	silver	7440-22-4	0.423	0.51	0.68	5112	6816
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com